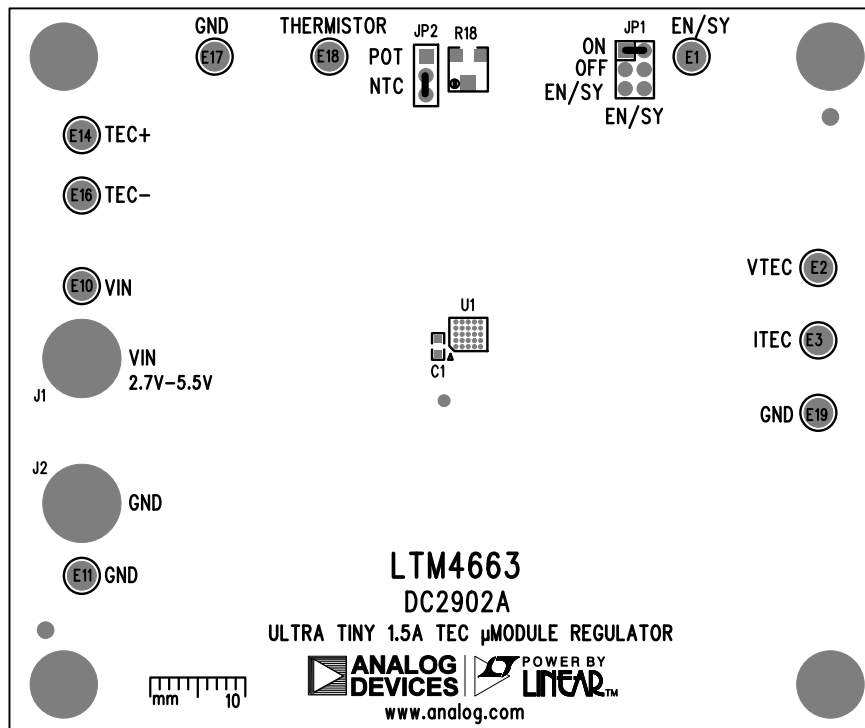
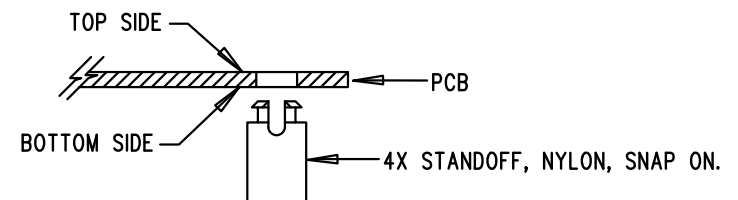


REVISION HISTORY				
ECO	REV	DESCRIPTION	APP. ENG.	DATE
-	2	PRODUCTION	CZ	10-09-19



## NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
5. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
6. INSTALL 4 STANDOFFS AT AS SHOWN BELOW:



APPROVALS		ANALOG DEVICES   POWER BY LINEAR™	
PCB DES.	LT	www.analog.com FOR ADI CUSTOMER USE ONLY	
APP ENG.	CZ	TITLE: TOP ASSEMBLY DRAWING	
		ULTRA TINY 1.5A TEC μMODULE REGULATOR	
		SIZE	REV.
		N/A	2
SCALE = NONE		IC NO. LTM4663EV DC2902A	FILENAME: DC2902A-2.PCB
		SHT 1 OF 2	